Silicon NPN Epitaxial

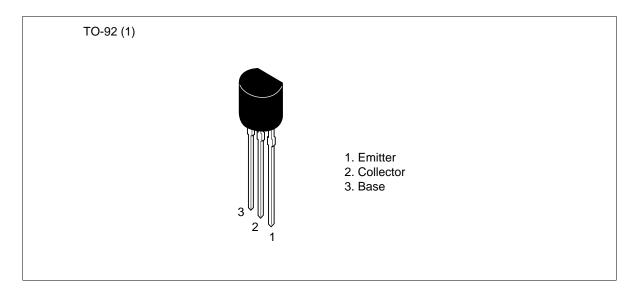
HITACHI

ADE-208-1062A (Z) 2nd. Edition Mar. 2001

Application

• Low frequency amplifier

Outline





Absolute Maximum Ratings $(Ta = 25^{\circ}C)$

Item	Symbol	2SC2396	2SC2543	2SC2544	Unit
Collector to base voltage	V_{CBO}	60	90	120	V
Collector to emitter voltage	V_{CEO}	60	90	120	V
Emitter to base voltage	V_{EBO}	5	5	5	V
Collector current	I _c	100	100	100	mA
Emitter current	I _E	-100	-100	-100	mA
Collector power dissipation	P _c	400	400	400	mW
Junction temperature	Tj	150	150	150	°C
Storage temperature	Tstg	-55 to +150	-55 to +150	-55 to +150	°C

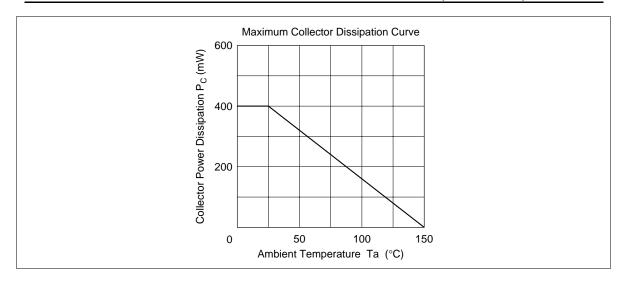
Electrical Characteristics ($Ta = 25^{\circ}C$)

		2SC2	2396		2SC	2543		2SC2544				
Item	Symbol	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	60	_	_	90	_	_	120	_	_	V	$I_{C} = 10 \ \mu\text{A}, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	60	_	_	90	_	_	120	_	_	V	$I_C = 1 \text{ mA},$ $R_{BE} = \infty$
Emitter to base breakdown voltage	V _{(BR)EBO}	5	_	_	5	_	_	5	_	_	V	$I_{E} = 10 \ \mu\text{A}, \ I_{C} = 0$
Collector cutoff current	I _{CBO}	_	_	0.1	_	_	0.1	_	_	0.1	μΑ	V _{CB} = 50 V, I _E = 0
Emitter cutoff current	I _{EBO}	_	_	0.1	_	_	0.1	_	_	0.1	μΑ	$V_{EB} = 2 \text{ V}, I_{C} = 0$
DC current transfer ratio	h _{FE} *1	250	_	1200	250	-	1200	250	_	800		$V_{CE} = 12 \text{ V},$ $I_{C} = 2 \text{ mA}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	_	0.2	_	-	0.2	_	_	0.2	V	$I_C = 10 \text{ mA},$ $I_B = 1 \text{ mA}$
Base to emitter voltage	V_{BE}	_	0.6	_	_	0.6	_	_	0.6	_	V	$V_{CE} = 12 \text{ V},$ $I_{C} = 2 \text{ mA}$
Gain bandwidth product	f _T		90	_	_	90	_	_	90	_	MHz	$V_{CE} = 12 \text{ V},$ $I_{C} = 2 \text{ mA}$
Collector output capacitance	Cob	_	3.0	_	_	3.0	_	_	3.0	_	pF	$V_{CB} = 10 \text{ V}, I_E = 0,$ f = 1 MHz

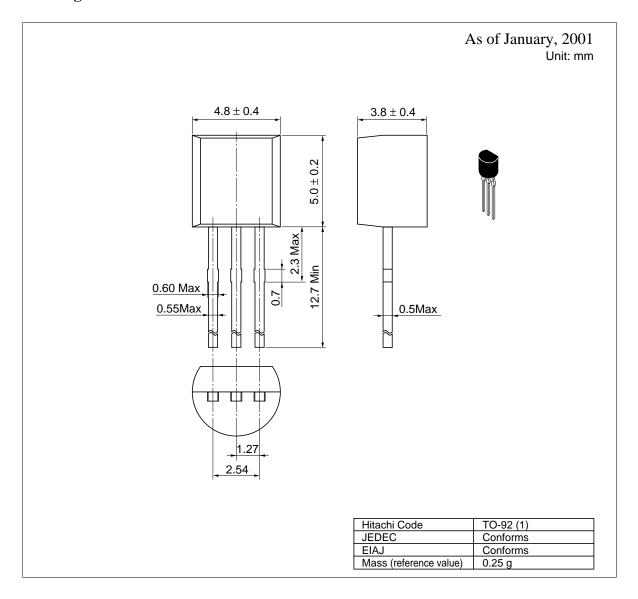
Note: 1. The 2SC2396, 2SC2543 and 2SC2544 are grouped by h_{FE1} as follows.

	D	E	F
2SC2396, 2SC2543	250 to 500	400 to 800	600 to 1200
2SC2544	250 to 500	400 to 800	_

See characteristic curves of 2SC2545, 2SC2546 and 2SC2547.



Package Dimensions



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